

BFP520F

Low profile high gain silicon NPN RF bipolar transistor



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Simulation



Support

Product description

The BFP520F is a low noise device based on a grounded emitter (SIEGET™) that is part of Infineon's established fifth generation RF bipolar transistor family. Its transition frequency f_T of 45 GHz, high gain and low noise make the device suitable for applications up to 15 GHz. It remains cost competitive without compromising on ease of use.



Feature list

- Minimum noise figure $NF_{min} = 0.95$ dB at 1.8 GHz, 2 V, 2 mA
- High gain $G_{ms} = 22.5$ dB at 1.8 GHz, 2 V, 20 mA
- $OIP_3 = 23.5$ dBm at 1.8 GHz, 2 V, 20 mA

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

- Radio-frequency oscillators such as local oscillator in LNB
- Broadband low noise amplifiers (LNAs) for CATV, DVB-T, DAB/DMB and FM/AM radio
- LNAs for wireless communications such as cordless phones

Device information

Table 1 Part information

Product name / Ordering code	Package	Pin configuration				Marking	Pieces / Reel
BFP520F / BFP520FH6327XTSA1	TSFP-4-1	1 = B	2 = E	3 = C	4 = E	APs	3000

Attention: *ESD (Electrostatic discharge) sensitive device, observe handling precautions*

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Absolute maximum ratings**1 Absolute maximum ratings****Table 2 Absolute maximum ratings at $T_A = 25^\circ\text{C}$ (unless otherwise specified)**

Parameter	Symbol	Values		Unit	Note or test condition
		Min.	Max.		
Collector emitter voltage	V_{CEO}	-	2.5	V	Open base
			2.4		$T_A = -55^\circ\text{C}$, open base
Collector emitter voltage			10		E-B short circuited
Collector base voltage			10		Open emitter
Emitter base voltage	V_{EBO}		1		Open collector
Base current	I_B	5	mA		-
Collector current	I_C	50			
Total power dissipation ¹⁾	P_{tot}	120	mW		$T_S \leq 98^\circ\text{C}$
Junction temperature	T_J	150	°C		-
Storage temperature	T_{Stg}				

Attention: *Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the integrated circuit.*

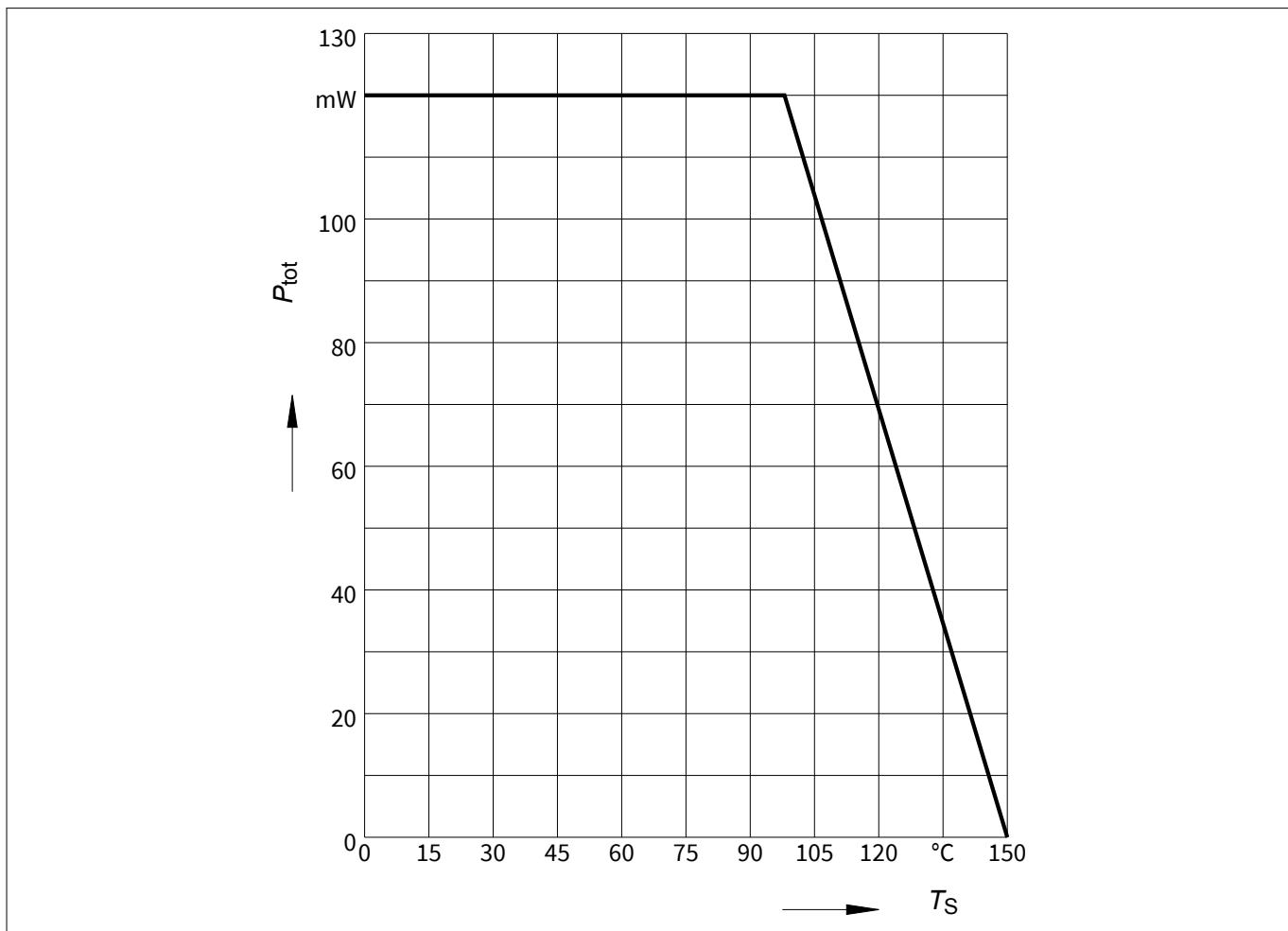
¹ T_S is the soldering point temperature. T_S is measured on the emitter lead at the soldering point of the PCB.

Thermal characteristics

2 Thermal characteristics

Table 3 Thermal resistance

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Junction - soldering point	R_{thJS}	–	430	–	K/W	–

**Figure 1****Total power dissipation $P_{tot} = f(T_S)$**

Electrical characteristics

3 Electrical characteristics

3.1 DC characteristics

Table 4 DC characteristics at $T_A = 25^\circ\text{C}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Collector emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	2.5	3	3.5	V	$I_C = 1 \text{ mA}$, $I_B = 0$, open base
Collector emitter leakage current	I_{CES}	-	-	$10^{\text{ 2)}}$	μA	$V_{\text{CE}} = 10 \text{ V}$, $V_{\text{BE}} = 0$, E-B short circuited
Collector base leakage current	I_{CBO}			$200^{\text{ 2)}}$	nA	$V_{\text{CB}} = 5 \text{ V}$, $I_E = 0$, open emitter
Emitter base leakage current	I_{EBO}			$35^{\text{ 2)}}$	μA	$V_{\text{EB}} = 1 \text{ V}$, $I_C = 0$, open collector
DC current gain	h_{FE}	70	110	170		$V_{\text{CE}} = 2 \text{ V}$, $I_C = 20 \text{ mA}$, pulse measured

3.2 General AC characteristics

Table 5 General AC characteristics at $T_A = 25^\circ\text{C}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Transition frequency	f_T	32	45	-	GHz	$V_{\text{CE}} = 2 \text{ V}$, $I_C = 30 \text{ mA}$, $f = 2 \text{ GHz}$
Collector base capacitance	C_{CB}	-	0.07	0.14	pF	$V_{\text{CB}} = 2 \text{ V}$, $V_{\text{BE}} = 0$, $f = 1 \text{ MHz}$, emitter grounded
Collector emitter capacitance	C_{CE}		0.25	-		$V_{\text{CE}} = 2 \text{ V}$, $V_{\text{BE}} = 0$, $f = 1 \text{ MHz}$, base grounded
Emitter base capacitance	C_{EB}		0.31			$V_{\text{EB}} = 0.5 \text{ V}$, $V_{\text{CB}} = 0$, $f = 1 \text{ MHz}$, collector grounded

² Maximum values not limited by the device but by the short cycle time of the 100% test.

Electrical characteristics

3.3 Frequency dependent AC characteristics

Measurement setup is a test fixture with Bias-T's in a $50\ \Omega$ system, $T_A = 25\text{ }^\circ\text{C}$.

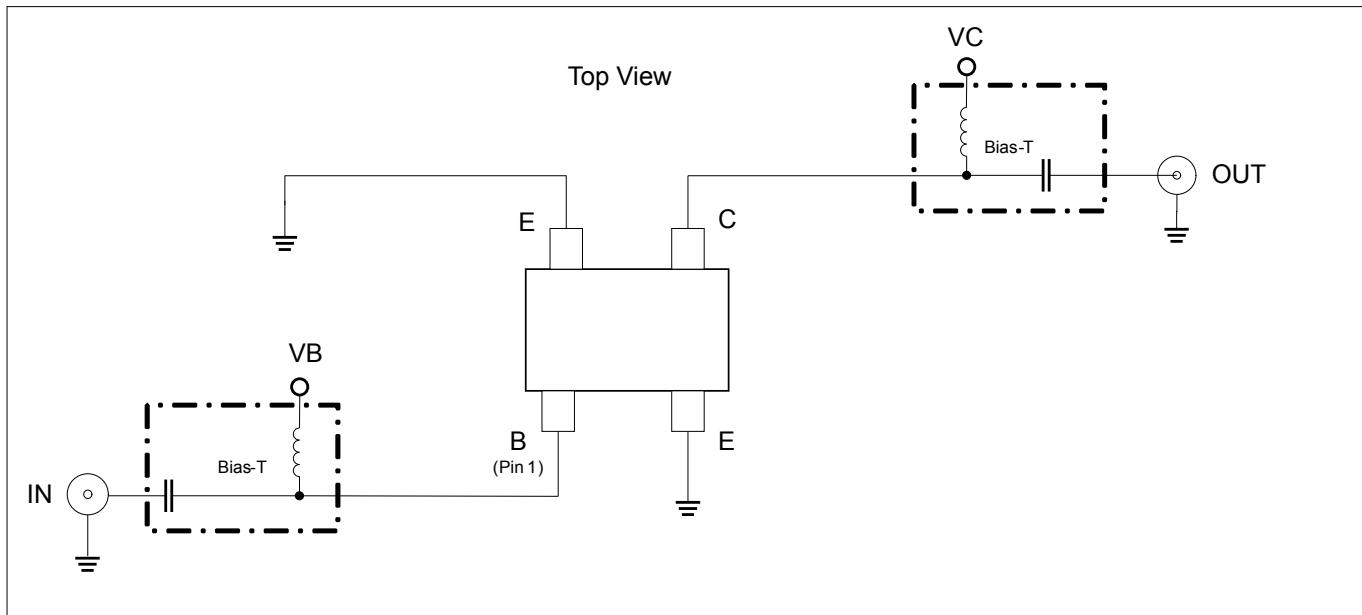


Figure 2 Testing circuit

Table 6 AC characteristics, $V_{CE} = 2\text{ V}$, $f = 1.8\text{ GHz}$

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Typ.	Max.		
Power gain		-		-	dB	
• Maximum power gain	G_{ms}		22.5			$I_C = 20\text{ mA}$
• Transducer gain	$ S_{21} ^2$		20.5			
Noise figure			0.95			$I_C = 2\text{ mA}$
• Minimum noise figure	NF_{min}					
Linearity					dBm	$Z_S = Z_{S,opt}$, $Z_L = Z_{L,opt}$, $I_C = 20\text{ mA}$
• 3rd order intercept point at output	OIP_3		23.5			
• 1 dB gain compression point at output	OP_{1dB}		10.5			

Note: $G_{ms} = |S_{21}| / S_{12}|$ for $k < 1$; $G_{ma} = |S_{21}| / S_{12}| / (k - (k^2 - 1)^{1/2})$ for $k > 1$. In order to get the NF_{min} values stated in this chapter, the test fixture losses have been subtracted from all measured results. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is $50\ \Omega$ from 0.1 MHz to 6 GHz .

Package information TSFP-4-1

4

Package information TSFP-4-1

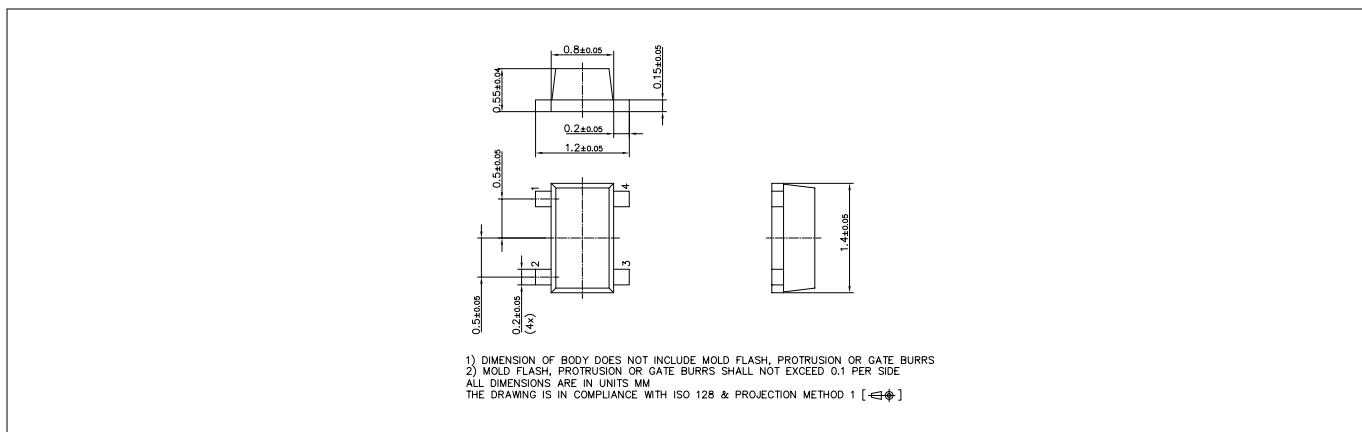


Figure 3 Package outline

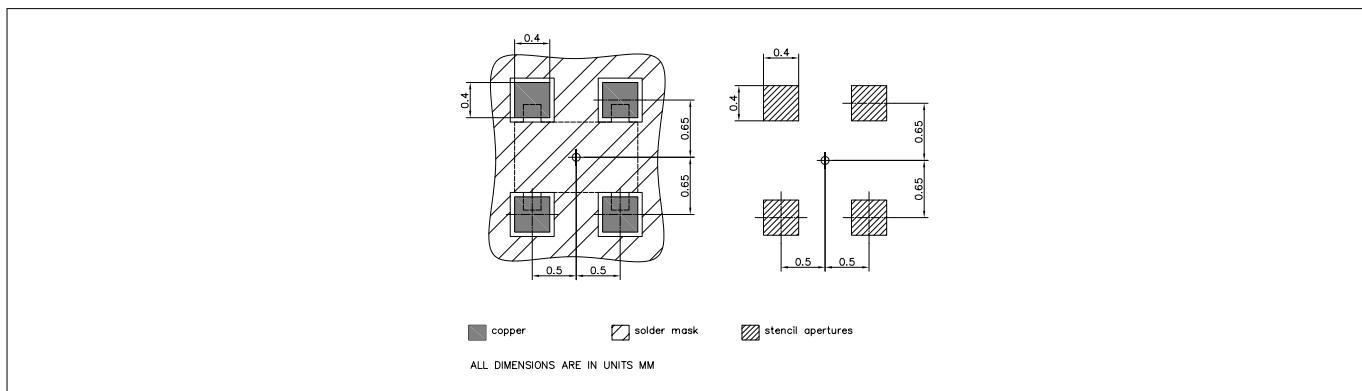


Figure 4 Foot print

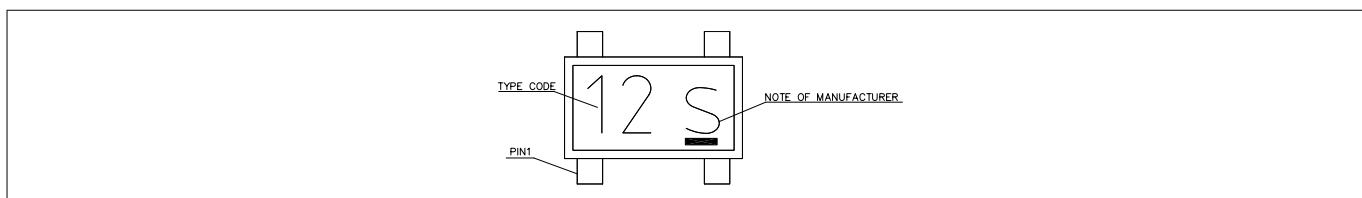


Figure 5 Marking layout example

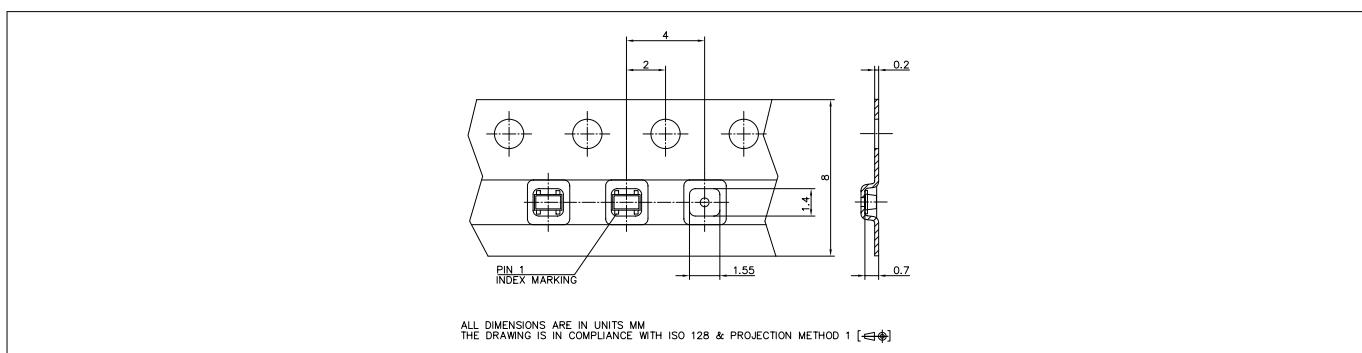


Figure 6 Tape dimensions

Revision history**Revision history**

Document version	Date of release	Description of changes
Revision 2.0	2019-01-25	New datasheet layout.